

# 400G QSFP-DD to 4x100G QSFP56 Active Optical Breakout Cable

## Features

- Up to 53.125Gbps Data Rate Per Channel by PAM4 Modulation
- Support 400GAUI-8 Electrical Interface (400G QSFP-DD)  
Support 100GAUI-2 Electrical Interface (100G QSFP56)
- Integrated 850nm VCSEL Array and PD Array
- DDM Function Implemented
- Hot-Pluggable QSFP-DD and QSFP56 Form Factor
- Power Dissipation:  $\leq 10W$  (400G End),  $\leq 3W$  (100G End)
- Single +3.3V Power Supply
- Operating Temperature Range: 0~ 70 °C

## Applications

- Data Centers and Cloud Networks
- Other Interconnect Requirement

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## Standards

- IEEE 802.3cd
- QSFP-DD MSA
- QSFP-DD-CMIS-Rev 4.0
- IEEE 802.3bs Annex120E
- SFF-8024 Rev. 4.6
- SFF-8679 Rev1.8
- SFF-8665 Rev1.9

## Description

The 400G QSFP-DD-4x100G QSFP56 breakout AOC is designed for relatively short connection, offering a low-cost, high-density solution alternative for system providers and customers implementing 400GE/ 100GE in Data Centers and Cloud Networks. This breakout cable is compliant with IEEE 802.3cd, OIF-CEI, QSFP-DD MSA, QSFP-DD-CMIS, IEEE 802.3bs Annex120E SFF-8024, SFF-8679, SFF-8665 standards.

## Absolute Maximum Ratings

**Table1-Absolute Maximum Ratings**

Parameter	Symbol	Min.	Typical	Max.	Unit	Note
Storage Temperature Range	TS	-20	-	+85	°C	
Relative Humidity	RH	0	-	85	%	
Power Supply Voltage	VCC	-0.5	-	+4.0	V	

## Recommended Operating Conditions

**Table2-Recommended Operating Conditions**

Parameter	Symbol	Unit.	Min	Typ.	Max	Note
Operating Case Temperature Range	Tca	°C	0		70	
Power Supply Voltage	VCC	V	3.135	3.3	3.465	
Bit Rate (per Channel )	BR	GBd		26.5625		
Humidity	Rh	%	5		85	
Fiber Bend Radius	Rb	cm	3			

## Electric Specifications (400G QSFP-DD and 100G QSFP56)

**Table3-Electrical Characteristics**

Parameter	Symbol	Unit	Min.	Typical	Max.	Note
Supply Voltage	VCC VCC3.3-Tx VCC3.3-Rx	V	3.135	3.3	3.465	
Power Consumption ( QSFP-DD)	Pc	W			11	Per-end
Power Consumption ( QSFP56)					5	

Transceiver Power-on Initialize Time		ms			2000	
<b>Transmitter</b>						
Differential Peak-to-peak input Voltage Tolerance		mV	900			
Differential Termination Mismatch					10%	
Differential Input Return Loss(SDD11)		dB			See CEI-56G- VSR	
Common-mode to Differential Conversion and Differential to Common-mode Conversion(SCD11, SDC11)		dB			See CEI-56G- VSR	
<b>Receiver</b>						
Differential Peak-to-peak Output Voltage		mV			900	
DC Common Mode Voltage	Vcm	mV	-0.35		2.85	
AC Common Mode Noise, RMS		mV			17.5	
Differential Termination Mismatch		%			10	
Differential Output Return Loss(SDD22)		dB			See CEI-56G- VSR	
Common-mode to Differential Conversion and Differential to Common-mode Conversion(SCD22, SDC22)		dB			See CEI-56G- VSR	
<b>IIC communication</b>						
IIC Clock Frequency ( QSFP-DD)		KHZ		400	1000	
IIC Clock Frequency ( QSFP56)				100		
Clock Stretching		us			500	
Data Hold Time		ns				

## Principle Diagram

### 1. 400G QSFP-DD

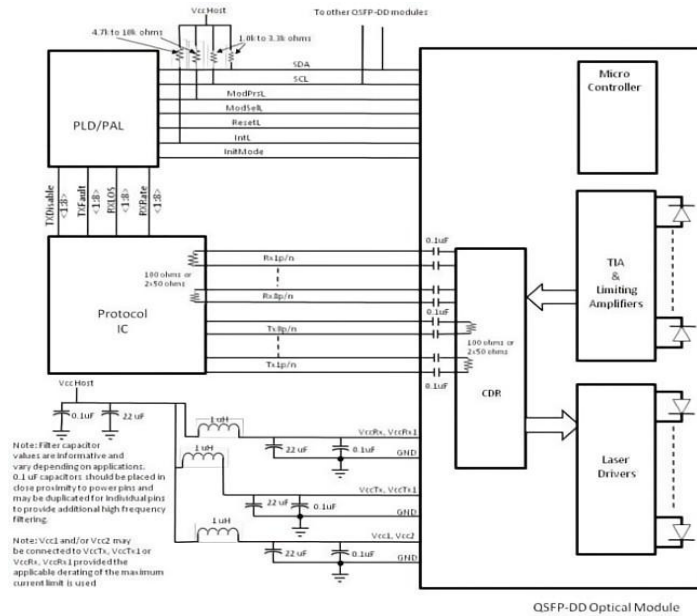


Figure 1 Module Principle Diagram

### 2. 100G QSFP56

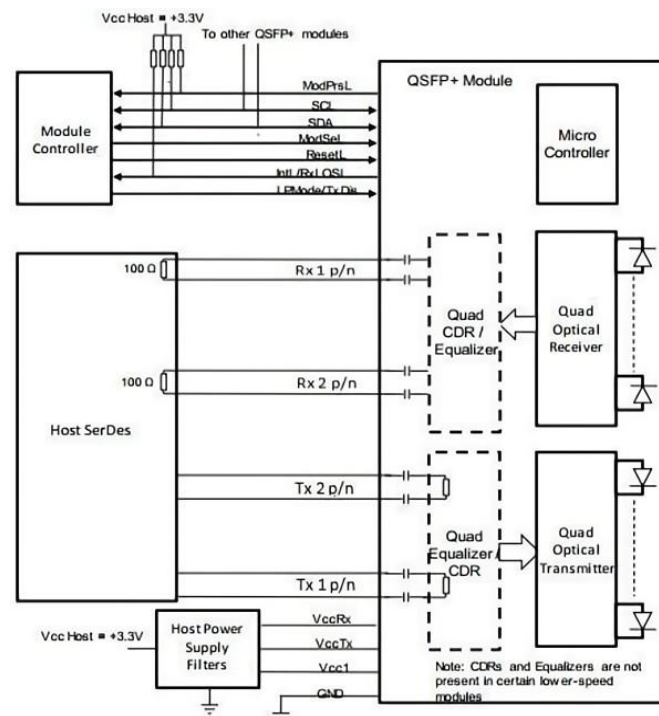


Figure 2 Module Principle Diagram

## Pin Descriptions

### 1. 400G QSFP-DD

**Table4- Pin Function Definition**

Pin	Logic	Symbol	Description	Notes
1		GND	Ground	1
2	CML-I	Tx2n	Transmitter Inverted Data Input	
3	CML-I	Tx2p	Transmitter Non-Inverted Data Input	
4		GND	Ground	1
5	CML-I	Tx4n	Transmitter Inverted Data Input	
6	CML-I	Tx4p	Transmitter Non-Inverted Data Input	
7		GND	Ground	1
8	LVTTL-I	ModSelL	Module Select	
9	LVTTL-I	ResetL	Module Reset	
10		Vcc Rx	+3.3V Power Supply Receiver	2
11	LVC MOS-I/O	SCL	2-wire serial interface clock	
12	LVC MOS-I/O	SDA	2-wire serial interface data	
13		GND	Ground	1
14	CML-O	Rx3p	Receiver Non-Inverted Data Output	
15	CML-O	Rx3n	Receiver Inverted Data Output	
16		GND	Ground	1
17	CML-O	Rx1p	Receiver Non-Inverted Data Output	1
18	CML-O	Rx1n	Receiver Inverted Data Output	1
19		GND	Ground	
20		GND	Ground	
21	CML-O	Rx2n	Receiver Inverted Data Output	1
22	CML-O	Rx2p	Receiver Non-Inverted Data Output	
23		GND	Ground	
24	CML-O	Rx4n	Receiver Inverted Data Output	1
25	CML-O	Rx4p	Receiver Non-Inverted Data Output	
26		GND	Ground	
27	LVTTL-O	ModPrsL	Module Present	2
28	LVTTL-O	IntL/RxLOSL	Interrupt. Optionally configurable as RxLOSL via the management interface (SFF-8636)	2
29		VccTx	+3.3V Power supply transmitter	
30		Vcc1	+3.3V Power supply	1
31	LVTTL-I	InitMode	Initialization mode; In legacy QSFP applications, the InitMode pad is called LPMODE	
32		GND	Ground	
33	CML-I	Tx3p	Transmitter Non-Inverted Data Input	1

34	CML-I	Tx3n	Transmitter Inverted Data Input	
35		GND	Ground	
36	CML-I	Tx1p	Transmitter Non-Inverted Data Input	1
37	CML-I	Tx1n	Transmitter Inverted Data Input	1
38		GND	Ground	
39		GND	Ground	
40	CML-I	Tx6n	Transmitter Inverted Data Input	
41	CML-I	Tx6p	Transmitter Non-Inverted Data Input	
42		GND	Ground	1
43	CML-I	Tx8n	Transmitter Inverted Data Input	
44	CML-I	Tx8p	Transmitter Non-Inverted Data Input	
45		GND	Ground	1
46		Reserved	For future use	3
47		VS1	Module Vendor Specific 1	3
48		VccRx1	3.3V Power Supply	2
49		VS2	Module Vendor Specific 2	3
50		VS3	Module Vendor Specific 3	3
51		GND	Ground	1
52	CML-O	Rx7p	Receiver Non-Inverted Data Output	
53	CML-O	Rx7n	Receiver Inverted Data Output	
54		GND	Ground	1
55	CML-O	Rx5p	Receiver Non-Inverted Data Output	
56	CML-O	Rx5n	Receiver Inverted Data Output	
57		GND	Ground	1
58		GND	Ground	1
59	CML-O	Rx6n	Receiver Inverted Data Output	
60	CML-O	Rx6p	Receiver Non-Inverted Data Output	
61		GND	Ground	1
62	CML-O	Rx8n	Receiver Inverted Data Output	
63	CML-O	Rx8p	Receiver Non-Inverted Data Output	
64		GND	Ground	1
65		NC	No Connect	3
66		Reserved	For future Use	3
67		VccTx1	3.3V Power Supply	2
68		Vcc2	3.3V Power Supply	2
69		Reserved	For future Use	3
70		GND	Ground	1
71	CML-I	Tx7p	Transmitter Non-Inverted Data Input	
72	CML-I	Tx7n	Transmitter Inverted Data Input	
73		GND	Ground	1
74	CML-I	Tx5p	Transmitter Non-Inverted Data Input	

75	CML-I	Tx5n	Transmitter Inverted Data Input	
76		GND	Ground	1

Notes:

1. QSFP-DD uses common ground (GND) for all signals and supply (power). All the common within the QSFP-DD module and all module voltages are referenced to this potential unless otherwise noted. Connected these directly to the host board signal common ground plane.
2. VCCRx, VCCRx 1, VCC1, VCC2, VCCTx, and VCCTx 1 shall be applied concurrently. Requirements defined for the host side of the Host Card Edge Connector are listed in Table 4. VCCRx, VCCRx 1, VCC 1, VCC2, VCCTx, and VCCTx 1 may be internally connected within the module in any combination. The connector Vcc pins are each rated for a maximum current of 1000mA.
3. All Vendor Specific, Reserved and No Connect pins may be terminated with 50 ohms to ground on the host. Pad 65 (No Connect) shall be left unconnected within the module. Vendor Specific and Reserved pads shall have an impedance to GND that is greater than 10kOhms and less than 100pF.

## Mechanical Dimensions

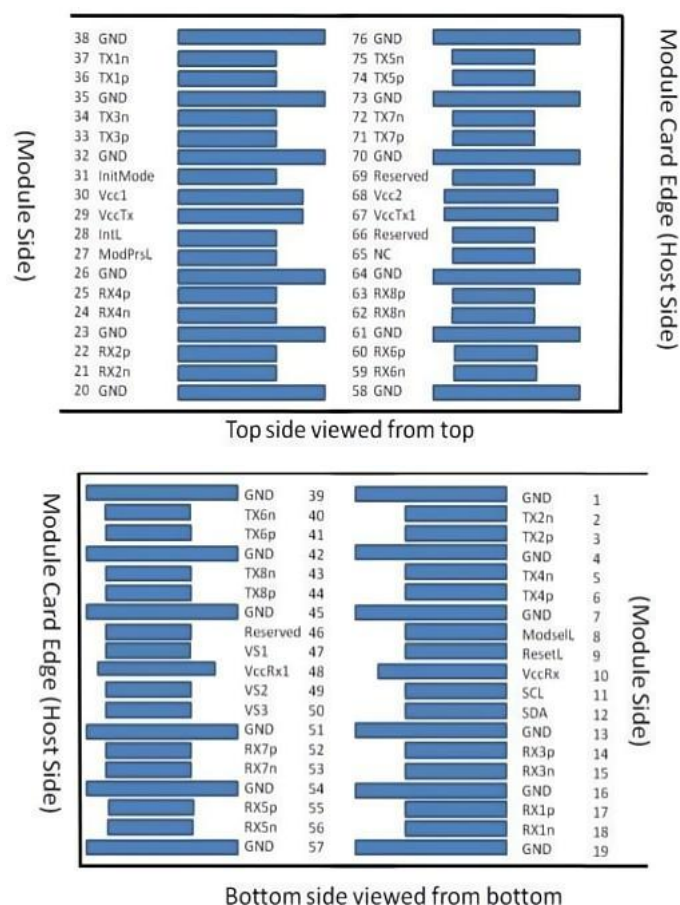


Figure 3. Electrical Pin-out Details

## 2.100G QSFP56

**Table5- Pin Function Definition**

Pin	Symbols	Logic	Description	Notes
1	GND		Ground	1
2	Tx2n	CML-I	Transmitter Inverted Data Input	
3	Tx2p	CML-I	Transmitter Non-Inverted Data Input	
4	GND		Ground	1
5	Tx4n	CML-I	Transmitter Inverted Data Input	
6	Tx4p	CML-I	Transmitter Non-Inverted Data Input	
7	GND		Ground	
8	ModSelL	LVTTL-I	Module Select	
9	ResetL	LVTTL-I	Module Reset	
10	Vcc Rx		+3.3V Power Supply Receiver	2
11	SCL	LVCOMS-I/O	2-wire serial interface clock	
12	SDA	LVCOMS-I/O	2-wire serial interface data	
13	GND		Ground	
14	Rx3p	CML-O	Receiver Non-Inverted Data Output	
15	Rx3n	CML-O	Receiver Inverted Data Output	
16	GND		Ground	1
17	Rx1p	CML-O	Receiver Non-Inverted Data Output	
18	Rx1n	CML-O	Receiver Inverted Data Output	1
19	GND		Ground	1
20	GND		Ground	
21	Rx2n	CML-O	Receiver Inverted Data Output	
22	Rx2p	CML-O	Receiver Non-Inverted Data Output	
23	GND		Ground	
24	Rx4n	CML-O	Receiver Inverted Data Output	
25	Rx4p	CML-O	Receiver Non-Inverted Data Output	
26	GND		Ground	1
27	ModPrsL	LVTTL-O	Module Present	
28	IntL	LVTTL-O	Interrupt	
29	VccTx		+3.3V Power supply transmitter	2
30	Vcc1		+3.3V Power supply	2
31	LPMode	LVTTL-I	Low Power Mode	
32	GND		Ground	1
33	Tx3p	CML-I	Transmitter Non-Inverted Data Input	
34	Tx3n	CML-I	Transmitter Inverted Data Input	
35	GND		Ground	1
36	Tx1p	CML-I	Transmitter Non-Inverted Data Input	
37	Tx1n	CML-I	Transmitter Inverted Data Input	



38	GND		Ground	1
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Notes:

1. GND is the symbol for signal and supply (power) common for the QSFP28 module. All are common within the module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal common ground plane. 2. VccRx, Vcc1 and VccTx are the receiving and transmission power suppliers and shall be applied concurrently. Recommended host board power supply filtering is shown in Figure 2 below. Vcc Rx, Vcc1 and Vcc Tx may be internally connected within the module in any combination. The connector pins are each rated for a maximum current of 1000mA.

## Mechanical Dimensions

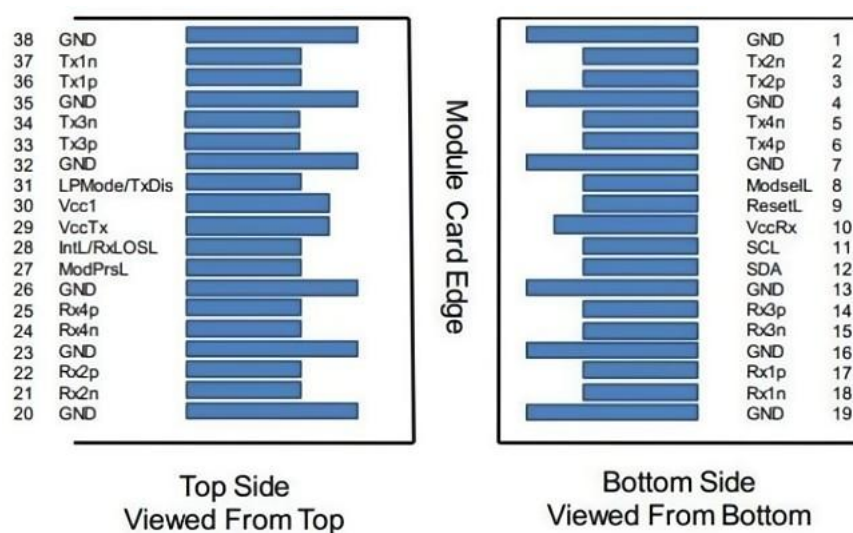


Figure 4. Electrical Pin-out Details

## Host Board Power Supply Filtering

### 1. 400G QSFP-DD

Any voltage drop across a filter network on the host is counted against the host DC set point accuracy specification. Inductors with DC Resistance of less than 0.1 Ohm should be used in order to maintain the required voltage at the Host Edge Card Connector.

Figure is the suggested transceiver/host interface.

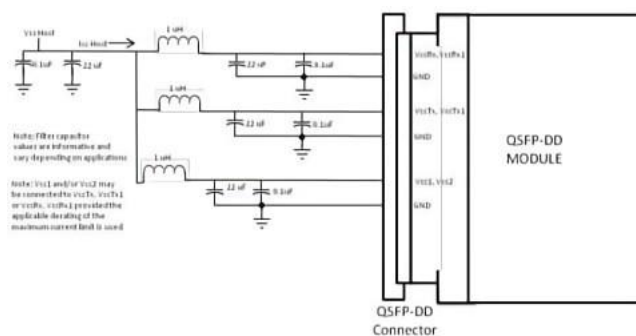


Figure 5. Recommended Host Board Power Supply Filtering

### 2. 200G QSFP56

Any voltage drop across a filter network on the host is counted against the host DC set point accuracy specification. Inductors with DC resistance of less than 0.1  $\Omega$  should be used in order to maintain the required voltage at the host edge card connector. It is recommended that the 22  $\mu$ F capacitors each have an equivalent series resistance of 0.22  $\Omega$ . The specification of the host power supply filtering network is beyond the scope of this specification, particularly because of the wide range of QSFP+ module Power Classes. Figure is the suggested transceiver/host interface.

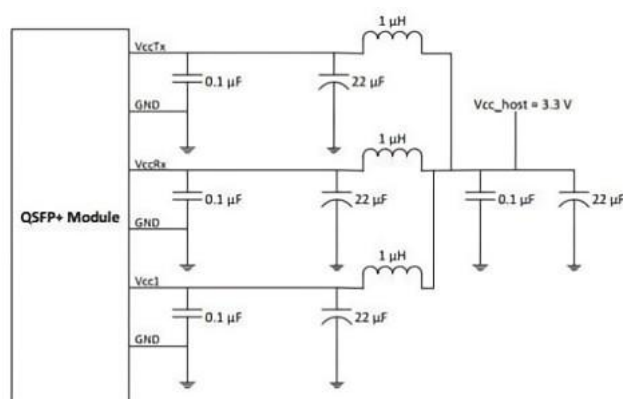


Figure 6. Recommended Host Board Power Supply Filtering

## Mechanical

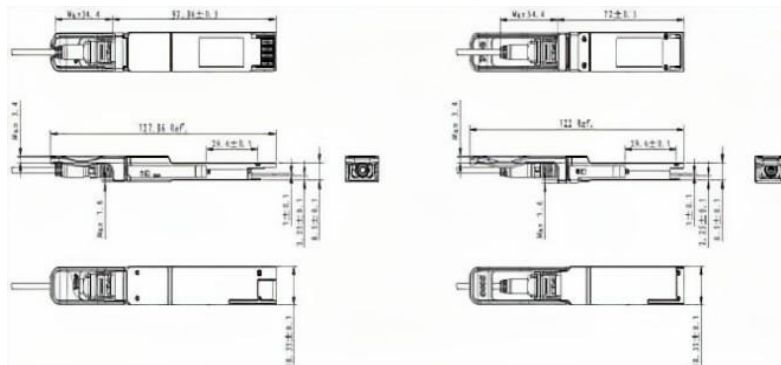


Figure 7. Package Outline

## Module Memory Map

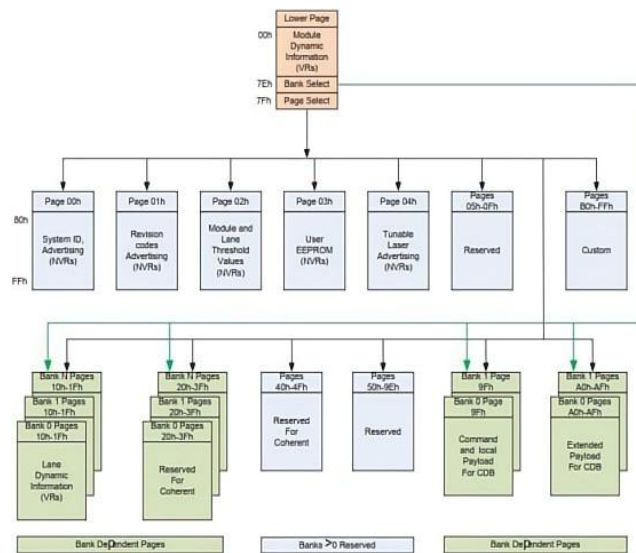


Figure 8. Digital Diagnostic Memory Map